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Details

Product Status	Last Time Buy
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	48
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	PG-TQFP-64
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc888cm8ffi5vacfxuma1

Summary of Features

XC886/888 Variant Devices

The XC886/888 product family features devices with different configurations, program memory sizes, package options, power supply voltage, temperature and quality profiles (Automotive or Industrial), to offer cost-effective solutions for different application requirements.

The list of XC886/888 device configurations are summarized in [Table 1](#). For each configuration, 2 types of packages are available:

- PG-TQFP-48, which is denoted by XC886 and;
- PG-TQFP-64, which is denoted by XC888.

Table 1 Device Configuration

Device Name	CAN Module	LIN BSL Support	MDU Module
XC886/888	No	No	No
XC886/888C	Yes	No	No
XC886/888CM	Yes	No	Yes
XC886/888LM	No	Yes	Yes
XC886/888CLM	Yes	Yes	Yes

Note: For variants with LIN BSL support, only LIN BSL is available regardless of the availability of the CAN module.

From these 10 different combinations of configuration and package type, each are further made available in many sales types, which are grouped according to device type, program memory sizes, power supply voltage, temperature and quality profile (Automotive or Industrial), as shown in [Table 2](#).

Table 2 Device Profile

Sales Type	Device Type	Program Memory (Kbytes)	Power Supply (V)	Temperature (°C)	Quality Profile
SAK-XC886*/888*-8FFA 5V	Flash	32	5.0	-40 to 125	Automotive
SAK-XC886*/888*-6FFA 5V	Flash	24	5.0	-40 to 125	Automotive
SAF-XC886*/888*-8FFA 5V	Flash	32	5.0	-40 to 85	Automotive
SAF-XC886*/888*-6FFA 5V	Flash	24	5.0	-40 to 85	Automotive
SAF-XC886*/888*-8FFI 5V	Flash	32	5.0	-40 to 85	Industrial
SAF-XC886*/888*-6FFI 5V	Flash	24	5.0	-40 to 85	Industrial

General Device Information

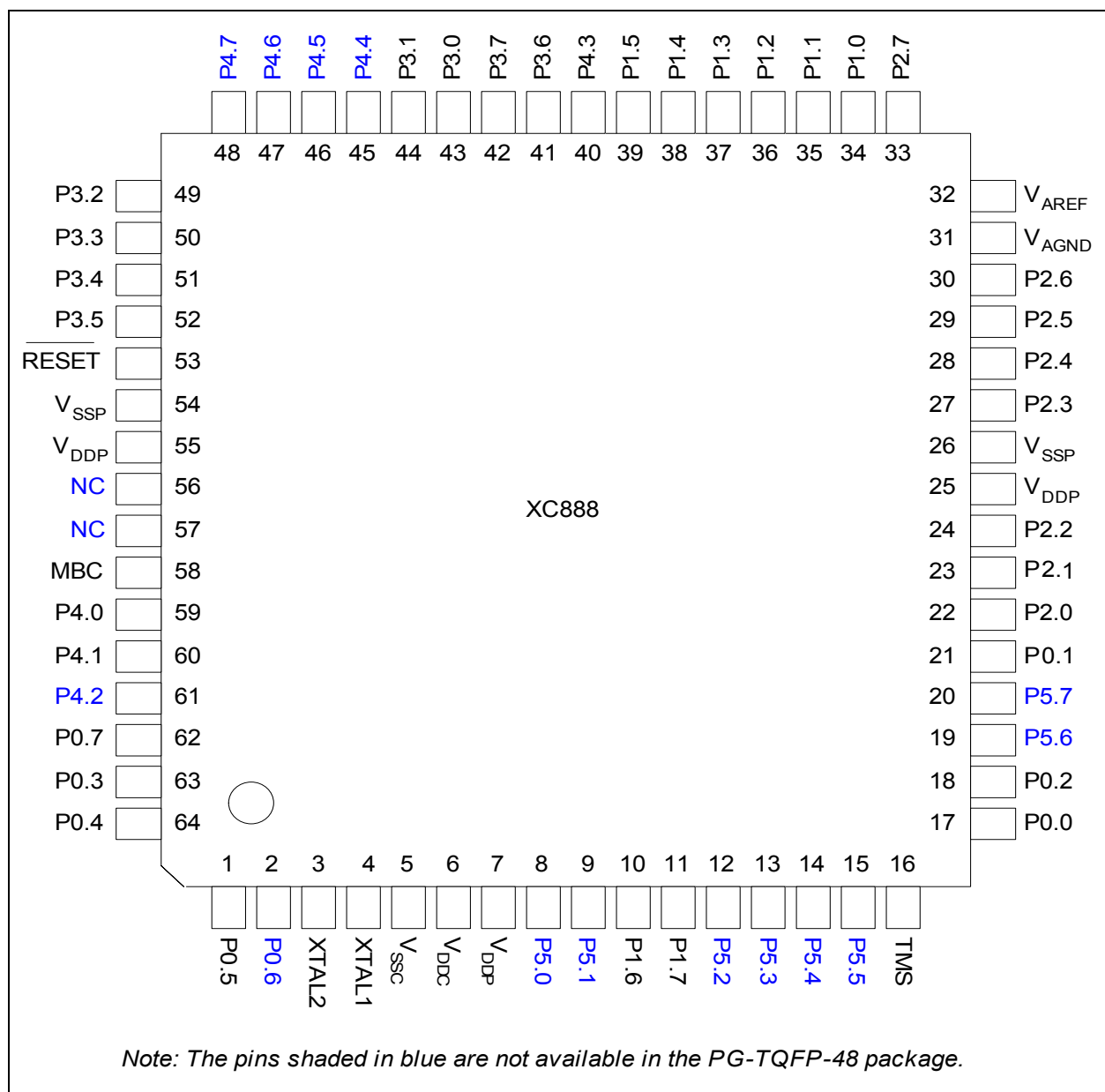


Figure 5 XC888 Pin Configuration, PG-TQFP-64 Package (top view)

General Device Information
Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function
P1		I/O		Port 1 Port 1 is an 8-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, Timer 0, Timer 1, Timer 2, Timer 21, MultiCAN and SSC.
P1.0	26/34		PU	RXD_0 UART Receive Data Input T2EX Timer 2 External Trigger Input RXDC0_0 MultiCAN Node 0 Receiver Input
P1.1	27/35		PU	EXINT3 External Interrupt Input 3 T0_1 Timer 0 Input TDO_1 JTAG Serial Data Output TXD_0 UART Transmit Data Output/Clock Output TXDC0_0 MultiCAN Node 0 Transmitter Output
P1.2	28/36		PU	SCK_0 SSC Clock Input/Output
P1.3	29/37		PU	MTSR_0 SSC Master Transmit Output/Slave Receive Input TXDC1_3 MultiCAN Node 1 Transmitter Output
P1.4	30/38		PU	MRST_0 SSC Master Receive Input/ Slave Transmit Output EXINT0_1 External Interrupt Input 0 RXDC1_3 MultiCAN Node 1 Receiver Input
P1.5	31/39		PU	CCPOS0_1 CCU6 Hall Input 0 EXINT5 External Interrupt Input 5 T1_1 Timer 1 Input EXF2_0 Timer 2 External Flag Output RXDO_0 UART Transmit Data Output

General Device Information
Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function
P3		I/O		Port 3 Port 3 is an 8-bit bidirectional general purpose I/O port. It can be used as alternate functions for CCU6, UART1, Timer 21 and MultiCAN.
P3.0	35/43		Hi-Z	CCPOS1_2 CCU6 Hall Input 1 CC60_0 Input/Output of Capture/Compare channel 0 RXDO1_1 UART1 Transmit Data Output
P3.1	36/44		Hi-Z	CCPOS0_2 CCU6 Hall Input 0 CC61_2 Input/Output of Capture/Compare channel 1 COUT60_0 Output of Capture/Compare channel 0 TXD1_1 UART1 Transmit Data Output/Clock Output
P3.2	37/49		Hi-Z	CCPOS2_2 CCU6 Hall Input 2 RXDC1_1 MultiCAN Node 1 Receiver Input RXD1_1 UART1 Receive Data Input CC61_0 Input/Output of Capture/Compare channel 1
P3.3	38/50		Hi-Z	COUT61_0 Output of Capture/Compare channel 1 TXDC1_1 MultiCAN Node 1 Transmitter Output
P3.4	39/51		Hi-Z	CC62_0 Input/Output of Capture/Compare channel 2 RXDC0_1 MultiCAN Node 0 Receiver Input T2EX1_0 Timer 21 External Trigger Input
P3.5	40/52		Hi-Z	COUT62_0 Output of Capture/Compare channel 2 EXF21_0 Timer 21 External Flag Output TXDC0_1 MultiCAN Node 0 Transmitter Output
P3.6	33/41		PD	CTRAP_0 CCU6 Trap Input

General Device Information
Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function
P3.7	34/42		Hi-Z	EXINT4 External Interrupt Input 4 COUT63_0 Output of Capture/Compare channel 3

Functional Description

The page register has the following definition:

MOD_PAGE

Page Register for module MOD

Reset Value: 00_H

7	6	5	4	3	2	1	0
OP		STNR		0	PAGE		
w		w		r	rw		

Field	Bits	Type	Description
PAGE	[2:0]	rw	Page Bits When written, the value indicates the new page. When read, the value indicates the currently active page.
STNR	[5:4]	w	Storage Number This number indicates which storage bit field is the target of the operation defined by bit field OP. If OP = 10 _B , the contents of PAGE are saved in STx before being overwritten with the new value. If OP = 11 _B , the contents of PAGE are overwritten by the contents of STx. The value written to the bit positions of PAGE is ignored. 00 ST0 is selected. 01 ST1 is selected. 10 ST2 is selected. 11 ST3 is selected.

Functional Description

3.2.4 XC886/888 Register Overview

The SFRs of the XC886/888 are organized into groups according to their functional units. The contents (bits) of the SFRs are summarized in [Chapter 3.2.4.1](#) to [Chapter 3.2.4.14](#).

Note: The addresses of the bitaddressable SFRs appear in bold typeface.

3.2.4.1 CPU Registers

The CPU SFRs can be accessed in both the standard and mapped memory areas (RMAP = 0 or 1).

Table 5 CPU Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0 or 1										
81 _H	SP Reset: 07_H Stack Pointer Register	Bit Field	SP							
		Type	rw							
82 _H	DPL Reset: 00_H Data Pointer Register Low	Bit Field	DPL7	DPL6	DPL5	DPL4	DPL3	DPL2	DPL1	DPL0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
83 _H	DPH Reset: 00_H Data Pointer Register High	Bit Field	DPH7	DPH6	DPH5	DPH4	DPH3	DPH2	DPH1	DPH0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
87 _H	PCON Reset: 00_H Power Control Register	Bit Field	SMOD	0			GF1	GF0	0	IDLE
		Type	rw	r			rw	rw	r	rw
88 _H	TCON Reset: 00_H Timer Control Register	Bit Field	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
		Type	rwh	rw	rwh	rw	rwh	rw	rwh	rw
89 _H	TMOD Reset: 00_H Timer Mode Register	Bit Field	GATE 1	T1S	T1M		GATE 0	T0S	T0M	
		Type	rw	rw	rw		rw	rw	rw	
8A _H	TL0 Reset: 00_H Timer 0 Register Low	Bit Field	VAL							
		Type	rwh							
8B _H	TL1 Reset: 00_H Timer 1 Register Low	Bit Field	VAL							
		Type	rwh							
8C _H	TH0 Reset: 00_H Timer 0 Register High	Bit Field	VAL							
		Type	rwh							
8D _H	TH1 Reset: 00_H Timer 1 Register High	Bit Field	VAL							
		Type	rwh							
98 _H	SCON Reset: 00_H Serial Channel Control Register	Bit Field	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
		Type	rw	rw	rw	rw	rw	rwh	rwh	rwh
99 _H	SBUF Reset: 00_H Serial Data Buffer Register	Bit Field	VAL							
		Type	rwh							
A2 _H	EO Reset: 00_H Extended Operation Register	Bit Field	0			TRAP_ EN	0			DPSE L0
		Type	r			rw	r			rw

Functional Description

Table 6 MDU Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
B3 _H	MR1 Reset: 00 _H MDU Result Register 1	Bit Field	DATA							
		Type	rh							
B4 _H	MD2 Reset: 00 _H MDU Operand Register 2	Bit Field	DATA							
		Type	rw							
B4 _H	MR2 Reset: 00 _H MDU Result Register 2	Bit Field	DATA							
		Type	rh							
B5 _H	MD3 Reset: 00 _H MDU Operand Register 3	Bit Field	DATA							
		Type	rw							
B5 _H	MR3 Reset: 00 _H MDU Result Register 3	Bit Field	DATA							
		Type	rh							
B6 _H	MD4 Reset: 00 _H MDU Operand Register 4	Bit Field	DATA							
		Type	rw							
B6 _H	MR4 Reset: 00 _H MDU Result Register 4	Bit Field	DATA							
		Type	rh							
B7 _H	MD5 Reset: 00 _H MDU Operand Register 5	Bit Field	DATA							
		Type	rw							
B7 _H	MR5 Reset: 00 _H MDU Result Register 5	Bit Field	DATA							
		Type	rh							

3.2.4.3 CORDIC Registers

The CORDIC SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 7 CORDIC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
9A _H	CD_CORDXL Reset: 00 _H CORDIC X Data Low Byte	Bit Field	DATAL							
		Type	rw							
9B _H	CD_CORDXH Reset: 00 _H CORDIC X Data High Byte	Bit Field	DATAH							
		Type	rw							
9C _H	CD_CORDYL Reset: 00 _H CORDIC Y Data Low Byte	Bit Field	DATAL							
		Type	rw							
9D _H	CD_CORDYH Reset: 00 _H CORDIC Y Data High Byte	Bit Field	DATAH							
		Type	rw							
9E _H	CD_CORDZL Reset: 00 _H CORDIC Z Data Low Byte	Bit Field	DATAL							
		Type	rw							
9F _H	CD_CORDZH Reset: 00 _H CORDIC Z Data High Byte	Bit Field	DATAH							
		Type	rw							

Functional Description
Table 9 WDT Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
BE _H	WDTL Reset: 00_H Watchdog Timer Register Low	Bit Field	WDT							
		Type	rh							
BF _H	WDTH Reset: 00_H Watchdog Timer Register High	Bit Field	WDT							
		Type	rh							

3.2.4.6 Port Registers

The Port SFRs can be accessed in the standard memory area (RMAP = 0).

Table 10 Port Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
B2 _H	PORT_PAGE Page Register Reset: 00_H	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rw		
RMAP = 0, PAGE 0										
80 _H	P0_DATA P0 Data Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
86 _H	P0_DIR P0 Direction Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
90 _H	P1_DATA P1 Data Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
91 _H	P1_DIR P1 Direction Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
92 _H	P5_DATA P5 Data Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
93 _H	P5_DIR P5 Direction Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
A0 _H	P2_DATA P2 Data Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
A1 _H	P2_DIR P2 Direction Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
B0 _H	P3_DATA P3 Data Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
B1 _H	P3_DIR P3 Direction Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
C8 _H	P4_DATA P4 Data Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
C9 _H	P4_DIR P4 Direction Register Reset: 00_H	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

Functional Description
Table 14 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FE _H	CCU6_CMPSTATL Reset: 00 _H Compare State Register Low	Bit Field	0	CC63 ST	CC POS2	CC POS1	CC POS0	CC62 ST	CC61 ST	CC60 ST
		Type	r	rh	rh	rh	rh	rh	rh	rh
FF _H	CCU6_CMPSTATH Reset: 00 _H Compare State Register High	Bit Field	T13IM	COU63PS	COU62PS	CC62 PS	COU61PS	CC61 PS	COU60PS	CC60 PS
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh

3.2.4.11 UART1 Registers

The UART1 SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 15 UART1 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
C8 _H	SCON Reset: 00_H Serial Channel Control Register	Bit Field	SM0	SM1	SM2	REN	TB8	RB8	TI	RI
		Type	rw	rw	rw	rw	rw	rwh	rwh	rwh
C9 _H	SBUF Reset: 00_H Serial Data Buffer Register	Bit Field	VAL							
		Type	rwh							
CA _H	BCON Reset: 00_H Baud Rate Control Register	Bit Field	0				BRPRE			R
		Type	r				rw			rw
CB _H	BG Reset: 00_H Baud Rate Timer/Reload Register	Bit Field	BR_VALUE							
		Type	rwh							
CC _H	FDCON Reset: 00_H Fractional Divider Control Register	Bit Field	0					NDOV	FDM	FDEN
		Type	r					rwh	rw	rw
CD _H	FDSTEP Reset: 00_H Fractional Divider Reload Register	Bit Field	STEP							
		Type	rw							
CE _H	FDRES Reset: 00_H Fractional Divider Result Register	Bit Field	RESULT							
		Type	rh							

Functional Description

3.3.3 Flash Programming Width

For the P-Flash banks, a programmed wordline (WL) must be erased before it can be reprogrammed as the Flash cells can only withstand one gate disturb. This means that the entire sector containing the WL must be erased since it is impossible to erase a single WL.

For the D-Flash bank, the same WL can be programmed twice before erasing is required as the Flash cells are able to withstand two gate disturbs. This means if the number of data bytes that needs to be written is smaller than the 32-byte minimum programming width, the user can opt to program this number of data bytes (x; where x can be any integer from 1 to 31) first and program the remaining bytes (32 - x) later. Hence, it is possible to program the same WL, for example, with 16 bytes of data two times (see [Figure 12](#))

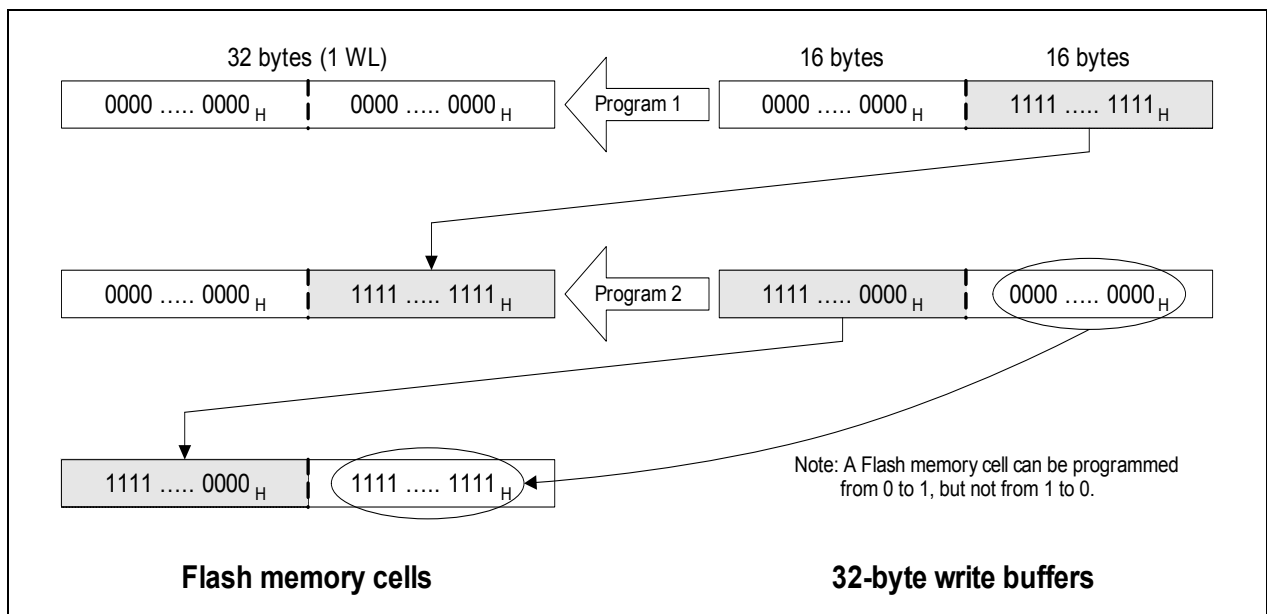


Figure 12 D-Flash Programming

Note: When programming a D-Flash WL the second time, the previously programmed Flash memory cells (whether 0s or 1s) should be reprogrammed with 0s to retain its original contents and to prevent “over-programming”.

Figure 19 shows the structure of a bidirectional port pin.

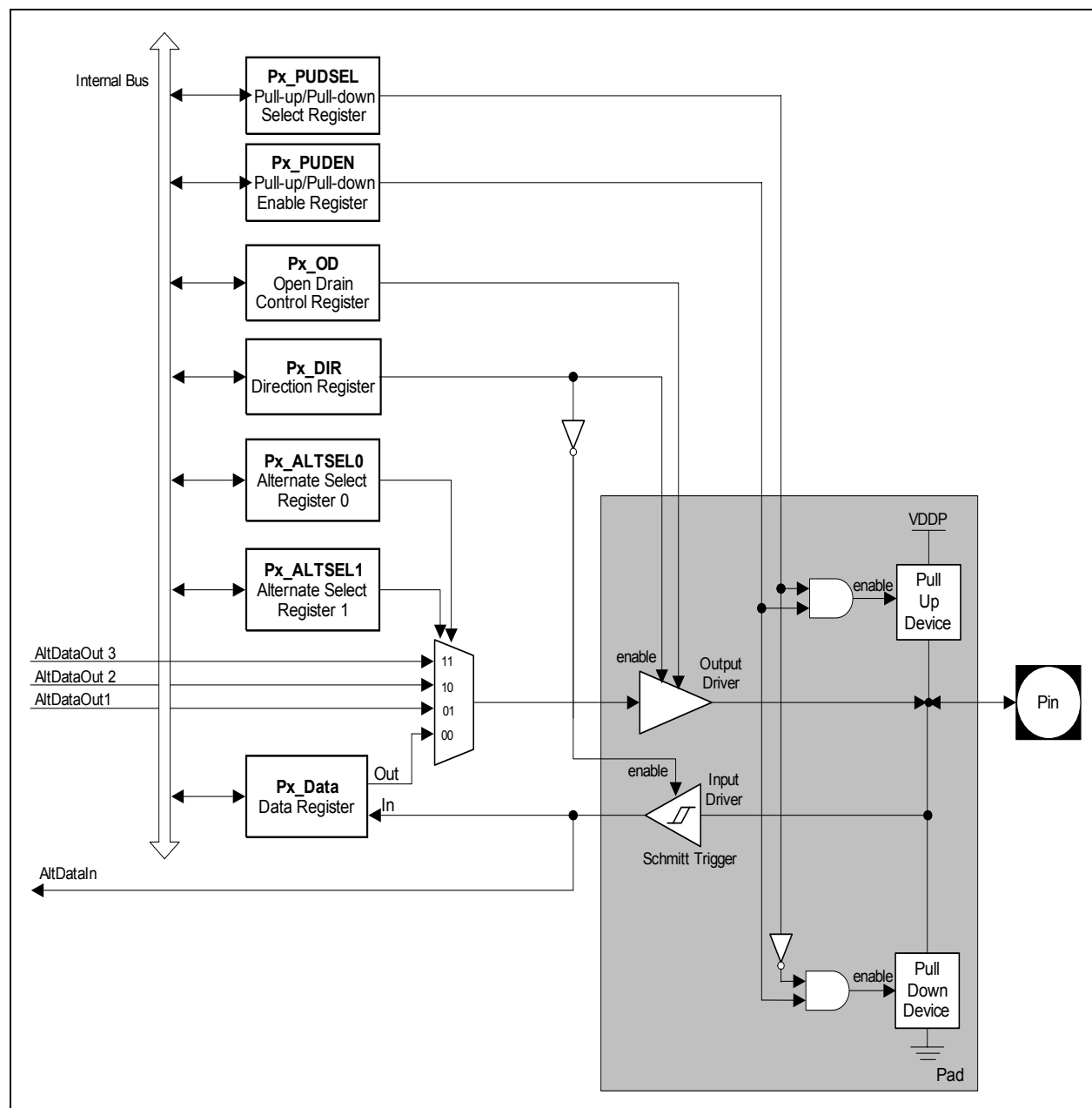


Figure 19 General Structure of Bidirectional Port

Functional Description

For power saving purposes, the clocks may be disabled or slowed down according to [Table 26](#).

Table 26 **System frequency ($f_{\text{sys}} = 96 \text{ MHz}$)**

Power Saving Mode	Action
Idle	Clock to the CPU is disabled.
Slow-down	Clocks to the CPU and all the peripherals are divided by a common programmable factor defined by bit field CMCON.CLKREL.
Power-down	Oscillator and PLL are switched off.

Functional Description

needed for the handshaking between the master and slave tasks is provided by the master task through the header portion of the frame.

The header consists of a break and synch pattern followed by an identifier. Among these three fields, only the break pattern cannot be transmitted as a normal 8-bit UART data. The break must contain a dominant value of 13 bits or more to ensure proper synchronization of slave nodes.

In the LIN communication, a slave task is required to be synchronized at the beginning of the protected identifier field of frame. For this purpose, every frame starts with a sequence consisting of a break field followed by a synch byte field. This sequence is unique and provides enough information for any slave task to detect the beginning of a new frame and be synchronized at the start of the identifier field.

Upon entering LIN communication, a connection is established and the transfer speed (baud rate) of the serial communication partner (host) is automatically synchronized in the following steps:

STEP 1: Initialize interface for reception and timer for baud rate measurement

STEP 2: Wait for an incoming LIN frame from host

STEP 3: Synchronize the baud rate to the host

STEP 4: Enter for Master Request Frame or for Slave Response Frame

*Note: Re-synchronization and setup of baud rate are always done for **every** Master Request Header or Slave Response Header LIN frame.*

Functional Description
3.23 Chip Identification Number

The XC886/888 identity (ID) register is located at Page 1 of address B3_H. The value of ID register is 09_H for Flash devices and 22_H for ROM devices. However, for easy identification of product variants, the Chip Identification Number, which is an unique number assigned to each product variant, is available. The differentiation is based on the product, variant type and device step information.

Two methods are provided to read a device's chip identification number:

- In-application subroutine, GET_CHIP_INFO
- Bootstrap loader (BSL) mode A

Table 36 lists the chip identification numbers of available XC886/888 Flash and ROM device variants.

Table 36 Chip Identification Number

Product Variant	Chip Identification Number		
	AA-Step	AB-Step	AC-Step
Flash Devices			
XC886CLM-8FFA 3V3	-	09500102 _H	0B500102 _H
XC888CLM-8FFA 3V3	-	09500103 _H	0B500103 _H
XC886LM-8FFA 3V3	-	09500122 _H	0B500122 _H
XC888LM-8FFA 3V3	-	09500123 _H	0B500123 _H
XC886CLM-6FFA 3V3	-	09551502 _H	0B551502 _H
XC888CLM-6FFA 3V3	-	09551503 _H	0B551503 _H
XC886LM-6FFA 3V3	-	09551522 _H	0B551522 _H
XC888LM-6FFA 3V3	-	09551523 _H	0B551523 _H
XC886CM-8FFA 3V3	-	09580102 _H	0B580102 _H
XC888CM-8FFA 3V3	-	09580103 _H	0B580103 _H
XC886C-8FFA 3V3	-	09580142 _H	0B580142 _H
XC888C-8FFA 3V3	-	09580143 _H	0B580143 _H
XC886-8FFA 3V3	-	09580162 _H	0B580162 _H
XC888-8FFA 3V3	-	09580163 _H	0B580163 _H
XC886CM-6FFA 3V3	-	095D1502 _H	0B5D1502 _H
XC888CM-6FFA 3V3	-	095D1503 _H	0B5D1503 _H
XC886C-6FFA 3V3	-	095D1542 _H	0B5D1542 _H
XC888C-6FFA 3V3	-	095D1543 _H	0B5D1543 _H

Functional Description
Table 36 Chip Identification Number (cont'd)

Product Variant	Chip Identification Number		
	AA-Step	AB-Step	AC-Step
XC886-6FFA 3V3	-	095D1562 _H	0B5D1562 _H
XC888-6FFA 3V3	-	095D1563 _H	0B5D1563 _H
XC886CLM-8FFA 5V	-	09900102 _H	0B900102 _H
XC888CLM-8FFA 5V	-	09900103 _H	0B900103 _H
XC886LM-8FFA 5V	-	09900122 _H	0B900122 _H
XC888LM-8FFA 5V	-	09900123 _H	0B900123 _H
XC886CLM-6FFA 5V	-	09951502 _H	0B951502 _H
XC888CLM-6FFA 5V	-	09951503 _H	0B951503 _H
XC886LM-6FFA 5V	-	09951522 _H	0B951522 _H
XC888LM-6FFA 5V	-	09951523 _H	0B951523 _H
XC886CM-8FFA 5V	-	09980102 _H	0B980102 _H
XC888CM-8FFA 5V	-	09980103 _H	0B980103 _H
XC886C-8FFA 5V	-	09980142 _H	0B980142 _H
XC888C-8FFA 5V	-	09980143 _H	0B980143 _H
XC886-8FFA 5V	-	09980162 _H	0B980162 _H
XC888-8FFA 5V	-	09980163 _H	0B980163 _H
XC886CM-6FFA 5V	-	099D1502 _H	0B9D1502 _H
XC888CM-6FFA 5V	-	099D1503 _H	0B9D1503 _H
XC886C-6FFA 5V	-	099D1542 _H	0B9D1542 _H
XC888C-6FFA 5V	-	099D1543 _H	0B9D1543 _H
XC886-6FFA 5V	-	099D1562 _H	0B9D1562 _H
XC888-6FFA 5V	-	099D1563 _H	0B9D1563 _H

ROM Devices

XC886CLM-8RFA 3V3	22400502 _H	-	-
XC888CLM-8RFA 3V3	22400503 _H	-	-
XC886LM-8RFA 3V3	22400522 _H	-	-
XC888LM-8RFA 3V3	22400523 _H	-	-
XC886CLM-6RFA 3V3	22411502 _H	-	-
XC888CLM-6RFA 3V3	22411503 _H	-	-

Electrical Parameters
Table 38 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
Input high voltage at XTAL1	V_{IHx}	SR	$0.7 \times V_{DDC}$	$V_{DDC} + 0.5$	V	
Pull-up current	I_{PU}	SR	–	-5	μA	$V_{IHP,min}$
			-50	–	μA	$V_{ILP,max}$
Pull-down current	I_{PD}	SR	–	5	μA	$V_{ILP,max}$
			50	–	μA	$V_{IHP,min}$
Input leakage current	I_{OZ1}	CC	-1	1	μA	$0 < V_{IN} < V_{DDP}$, $T_A \leq 125^\circ C^{2)}$
Input current at XTAL1	I_{ILx}	CC	- 10	10	μA	
Overload current on any pin	I_{OV}	SR	-5	5	mA	
Absolute sum of overload currents	$\Sigma I_{OV} $	SR	–	25	mA	³⁾
Voltage on any pin during V_{DDP} power off	V_{PO}	SR	–	0.3	V	⁴⁾
Maximum current per pin (excluding V_{DDP} and V_{SS})	I_M	SR SR	–	15	mA	
Maximum current for all pins (excluding V_{DDP} and V_{SS})	$\Sigma I_M $	SR	–	90	mA	
Maximum current into V_{DDP}	I_{MVDDP}	SR	–	120	mA	³⁾
Maximum current out of V_{SS}	I_{MVSS}	SR	–	120	mA	³⁾

1) Not subjected to production test, verified by design/characterization. Hysteresis is implemented to avoid meta stable states and switching due to internal ground bounce. It cannot be guaranteed that it suppresses switching due to external system noise.

2) An additional error current (I_{INU}) will flow if an overload current flows through an adjacent pin. TMS pin and RESET pin have internal pull devices and are not included in the input leakage current characteristic.

3) Not subjected to production test, verified by design/characterization.

4) Not subjected to production test, verified by design/characterization. However, for applications with strict low power-down current requirements, it is mandatory that no active voltage source is supplied at any GPIO pin when V_{DDP} is powered off.

Electrical Parameters

4.3.3 Power-on Reset and PLL Timing

Table 49 provides the characteristics of the power-on reset and PLL timing in the XC886/888.

Table 46 Power-On Reset and PLL Timing (Operating Conditions apply)

Parameter	Symbol		Limit Values			Unit	Test Conditions
			min.	typ.	max.		
Pad operating voltage	V_{PAD}	CC	2.3	–	–	V	¹⁾
On-Chip Oscillator start-up time	t_{OSCST}	CC	–	–	500	ns	¹⁾
Flash initialization time	t_{FINIT}	CC	–	160	–	μs	¹⁾
RESET hold time	t_{RST}	SR	–	500	–	μs	V_{DDP} rise time (10% – 90%) ≤ 500μs ¹⁾²⁾
PLL lock-in in time	t_{LOCK}	CC	–	–	200	μs	¹⁾
PLL accumulated jitter	D_P		–	–	0.7	ns	¹⁾³⁾

1) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

2) RESET signal has to be active (low) until V_{DDC} has reached 90% of its maximum value (typ. 2.5 V).

3) PLL lock at 96 MHz using a 4 MHz external oscillator. The PLL Divider settings are K = 2, N = 48 and P = 1.

Electrical Parameters

Table 50 JTAG Timing (Operating Conditions apply; CL = 50 pF) (cont'd)

Parameter	Symbol	Limits		Unit	Test Conditions
		min	max		
TDO high impedance to valid output from TCK	t_4 CC	-	27	ns	5V Device ¹⁾
		-	36	ns	3.3V Device ¹⁾
TDO valid output to high impedance from TCK	t_5 CC	-	22	ns	5V Device ¹⁾
		-	28	ns	3.3V Device ¹⁾

1) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

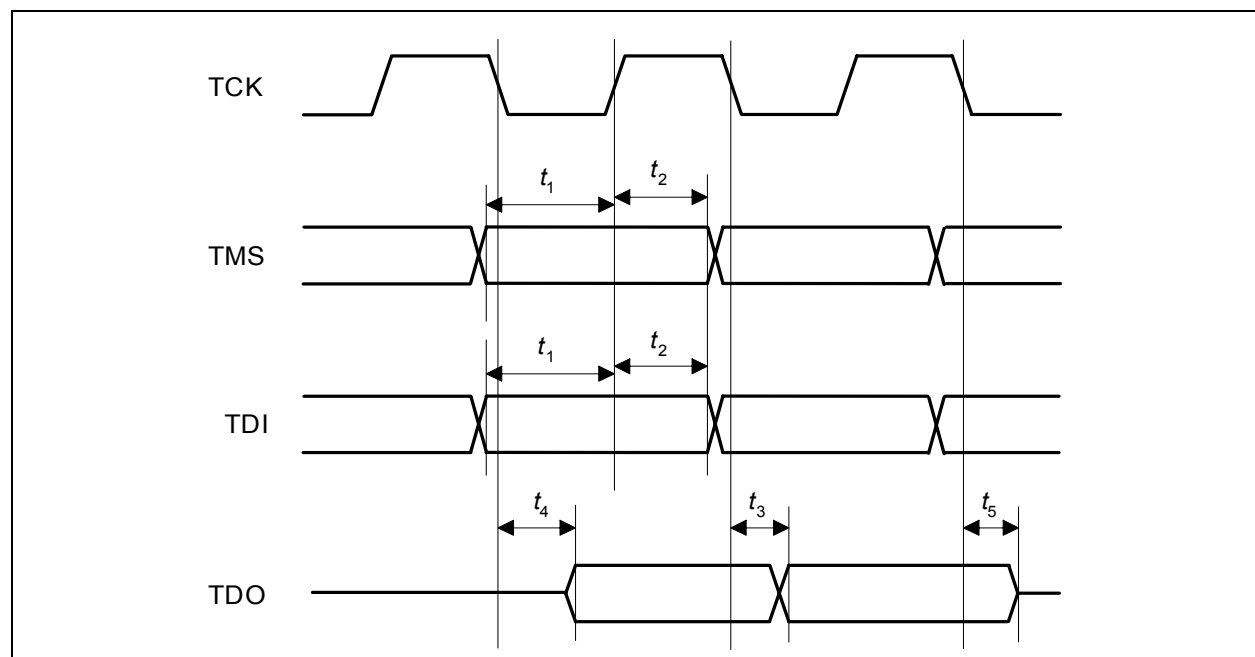





Figure 47 JTAG Timing

4.3.7 SSC Master Mode Timing

Table 51 provides the characteristics of the SSC timing in the XC886/888.

Table 51 SSC Master Mode Timing (Operating Conditions apply; CL = 50 pF)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
SCLK clock period	t_0	CC	$2 \cdot T_{SSC}$	–	ns	1)2)
MTSR delay from SCLK 	t_1	CC	0	8	ns	2)
MRST setup to SCLK 	t_2	SR	24	–	ns	2)
MRST hold from SCLK 	t_3	SR	0	–	ns	2)

1) $T_{SSCmin} = T_{CPU} = 1/f_{CPU}$. When $f_{CPU} = 24$ MHz, $t_0 = 83.3$ ns. T_{CPU} is the CPU clock period.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

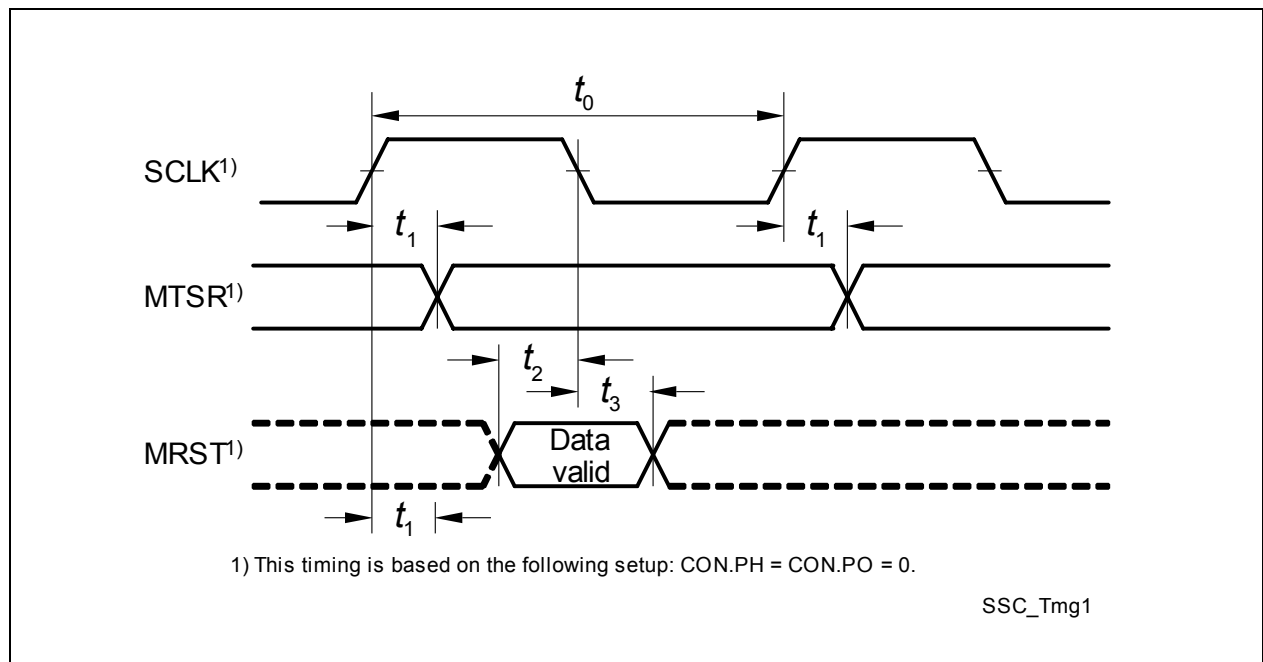


Figure 52 SSC Master Mode Timing